

1 **Optimizing Dielectric, Mechanical, and Thermal Properties of**
2 **Epoxy Resin through Molecular Design for Multifunctional**
3 **Performance**

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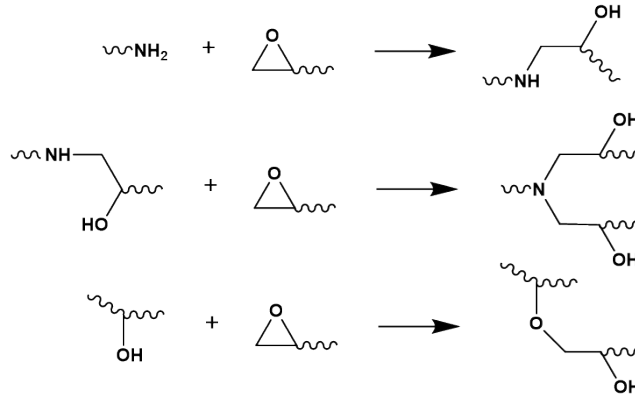
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19 **1 Structure of epoxy resin**

20 In this study, the amine/epoxy resin system consisting of resin solution (ARALDITE®
21 LY 5052) and amine hardener (ARADUR® 5052 CH) are used. The curing reaction in
22 this system, along with the resulting crosslinked polymer network^{1,2}, is illustrated in
23 **Figure S1**.

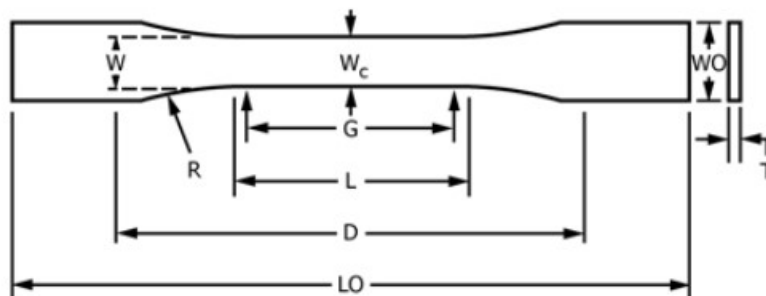


25 **Figure S1.** Main reaction between epoxy resin and hardener used in this study.

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27 **2 Dimensions of tensile specimens.**

28 The tensile measurement was conducted based on ASTM D638 test standard³. The
29 dimension of the specimen is described as Type V in this standard:



31 **Figure S2.** Dimensions of tensile testing samples

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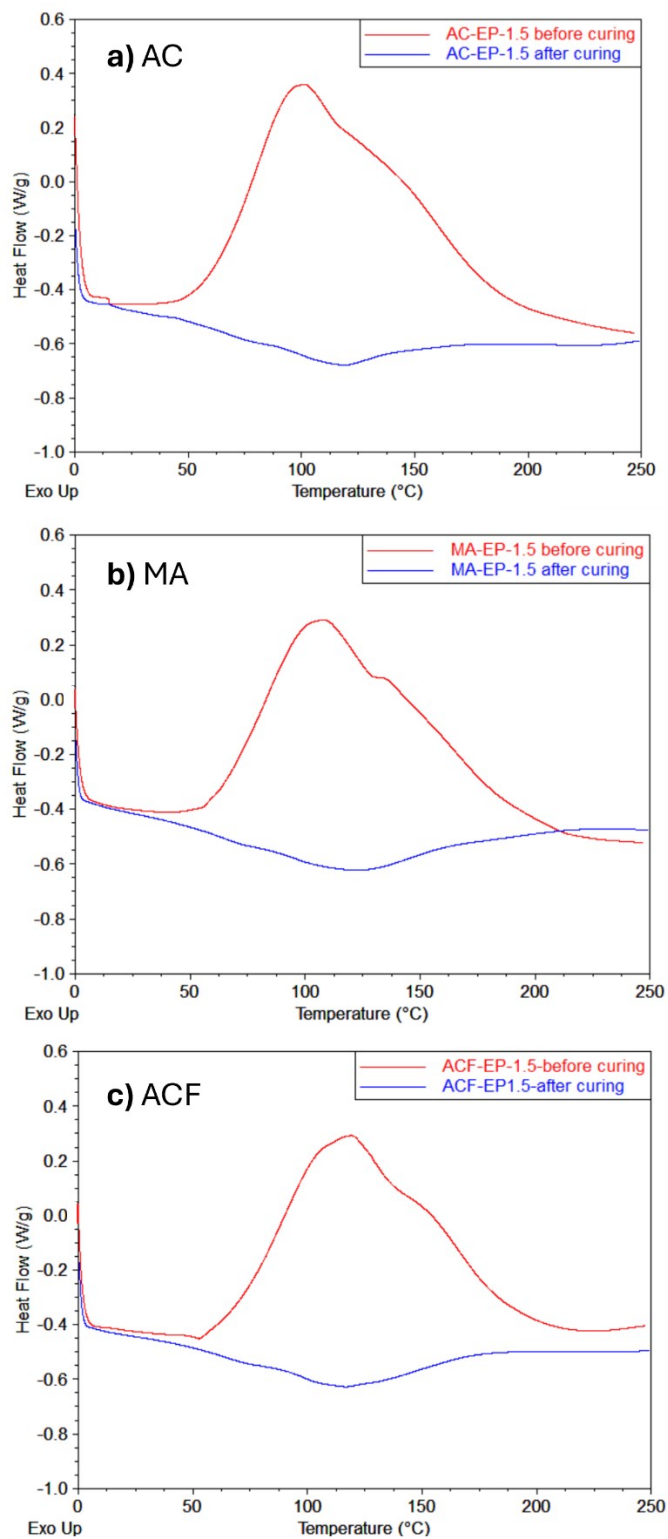
33 **Table S1.** Dimensions of tensile testing samples

Dimensions (see drawing)	Specimen dimensions (mm)
W—Width of the narrow section	3.18
L—Length of the narrow section	9.53
WO—Width overall	9.53
LO—Length overall	63.5
G—Gage length	7.62
D—Distance between grips	25.4
R—Radius of fillet	12.7

34

35 **3 Curing behavior of modified EP**

36 The DSC curves for all uncured and cured modified EP with 1.5 wt.% modifier
 37 concentration are illustrated in **Figure S3**, illustrated complete curing for all modified EP
 38 using the given curing conditions in this study.



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40 **Figure S3.** DSC curves for uncured and cured (a) EP-AC-1.5, (b) EP-MA-1.5, and (c) EP-ACF-

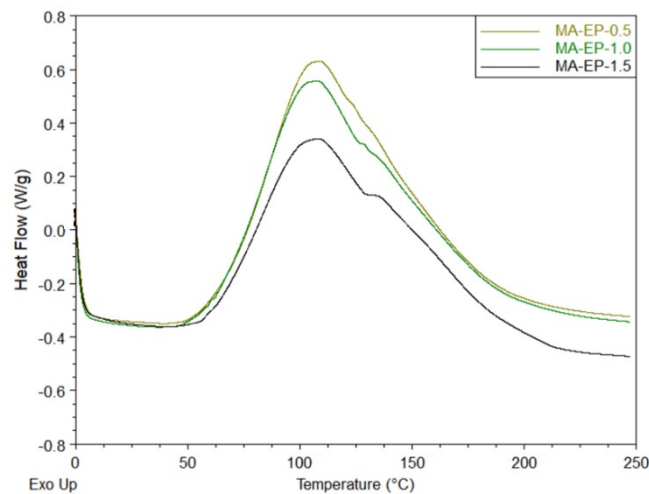
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1.5.

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43 4 Heat released in curing process of EP-MA

44 The curing process was investigated by differential scanning calorimetry (DSC). The
45 exothermic peak can be observed in the curing process, as shown in **Figure S4**. As the
46 concentration of MA increases, the heat of curing decreases from 432 J/g (EP-MA-0.5)
47 to 409 J/g (EP-MA-1.0) and to 340 J/g (EP-MA-1.5), indicating reduced crosslinking due
48 to excess modifier.



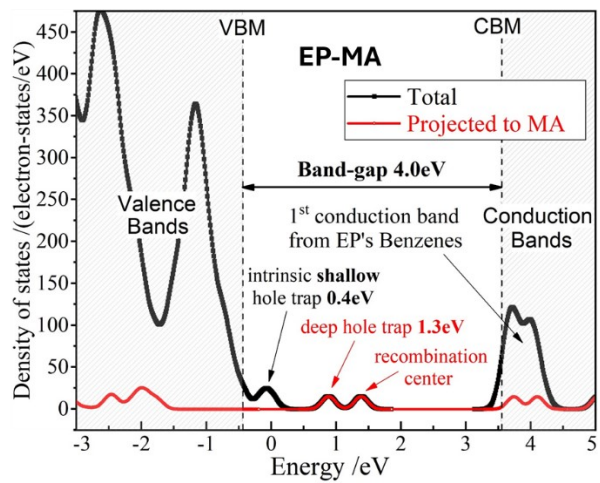
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50 **Figure S4.** Exothermic peaks in curing process for EP-MA with various modifier
51 concentrations.

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53 5 First principles calculation for charge trap in EP-MA

54 First principles calculations indicate that MA introduces deep hole traps at 1.3 eV in the
55 modified EP, as illustrated in **Figure S5**.



56

57 **Figure S5.** Density of electron states for EP-MA calculated through first-principal.

58

59 **Reference**

- 60 1 R. Ramsdale-Capper and J. P. Foreman, *Polymer*, 2018, **146**, 321–330.
61 2 J. P. Bell, *Journal of Polymer Science Part A-2: Polymer Physics*, 1970, **8**, 417–436.
62 3 D20 Committee, *Test Method for Tensile Properties of Plastics*, ASTM International.
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